EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	26	"204802"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 10:59
L2	469	microfeature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 10:59
L3	1	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:12
L5	2	"6,836,009".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:16
L6	2	"5,677,566".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:25
L7	332361	(die dice semiconductor microprocessor chip ic (integrated adj circuit) element electronic) with (lead leadframe (lead adj (finger frame)) leadfinger)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:30
L8	38700	(solder ball bump bga) same 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:31
L9	15339	(stack$5 mount$5 multi multilevel) same 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:31

L10	332367	(die dice semiconductor microfeature microprocessor chip ic (integrated adj circuit) element electronic) with (lead leadframe (lead adj (finger frame)) leadfinger)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:30
L11	20168	(ball bump bga) same 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:31
L12	7971	(stack$5 mount$5 multi multilevel) same 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:35
L13	3334	12 same packag$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:36
L14	2132	(contact pad terminal electrode) same 13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:36
L15	9710	(stack$5 mount$5 multi multilevel plural$4) same 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:35
L16	4049	15 same packag$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:36
L17	2727	(contact pad terminal electrode) same 16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:37

L18	2323	solder$3 and 17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:37
L19	1901	(encase encapsulat$4 resin epoxy) and 18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 11:38